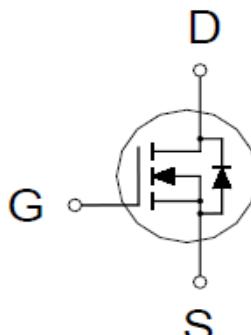
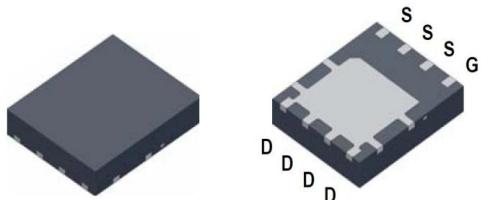


PK648BA

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
30V	3.4mΩ @ $V_{GS} = 10V$	75A



PDFN 5X6P

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ³	$T_C = 25^\circ C$	I_D	75	A
	$T_C = 100^\circ C$		47	
Pulsed Drain Current ¹		I_{DM}	150	A
Continuous Drain Current	$T_A = 25^\circ C$	I_D	19.8	
	$T_A = 70^\circ C$		15.8	
Avalanche Current		I_{AS}	37	
Avalanche Energy	$L = 0.1mH$	E_{AS}	71	mJ
Power Dissipation	$T_C = 25^\circ C$	P_D	35	W
	$T_C = 100^\circ C$		14	
Power Dissipation	$T_A = 25^\circ C$	P_D	2.4	W
	$T_A = 70^\circ C$		1.5	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$	52	3.6	°C / W
Junction-to-Case	$R_{\theta JC}$			

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

³Package limitation current is 26A.

PK648BA

N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.35	1.75	2.35	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			10	
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$		3.3	5.2	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 18\text{A}$		2.6	3.4	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 18\text{A}$		60		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$		2071		pF
Output Capacitance	C_{oss}			329		
Reverse Transfer Capacitance	C_{rss}			225		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		1.9		Ω
Total Gate Charge ²	Q_g	$V_{\text{GS}} = 10\text{V}$		40.9		nC
		$V_{\text{GS}} = 4.5\text{V}$		21.2		
Gate-Source Charge ²	Q_{gs}	$V_{\text{DS}} = 15\text{V}, I_D = 18\text{A}$		6.3		nC
Gate-Drain Charge ²	Q_{gd}			9.6		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$			26		nS
Rise Time ²	t_r			12		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$	$I_D \geq 18\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		50		nS
Fall Time ²	t_f			10		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current ³	I_S				35	A
Forward Voltage ¹	V_{SD}	$I_F = 18\text{A}, V_{\text{GS}} = 0\text{V}$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 18\text{A}, dI_F/dt = 100\text{A} / \mu\text{s}$		25		nS
Reverse Recovery Charge	Q_{rr}			12		nC

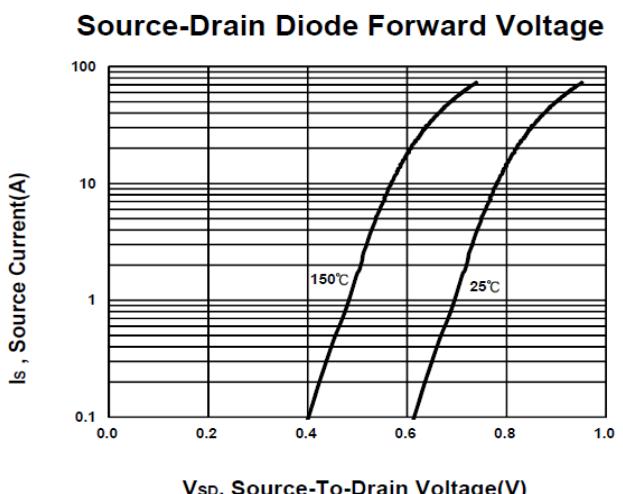
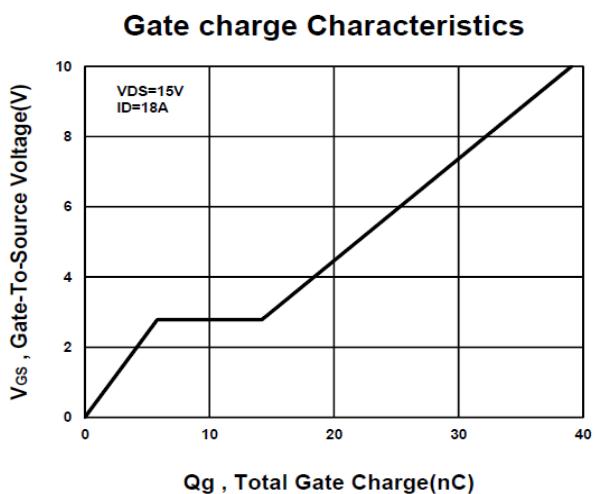
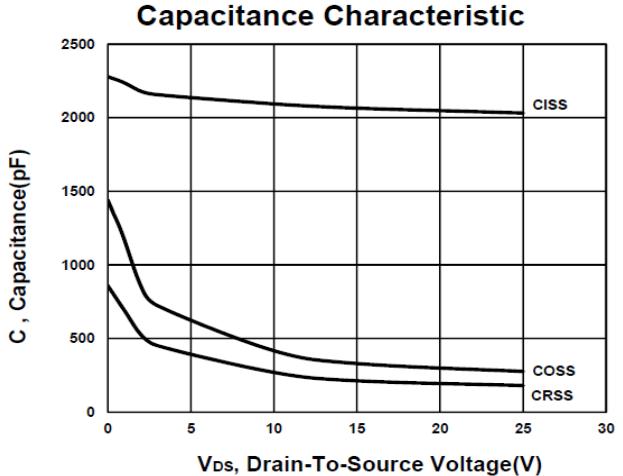
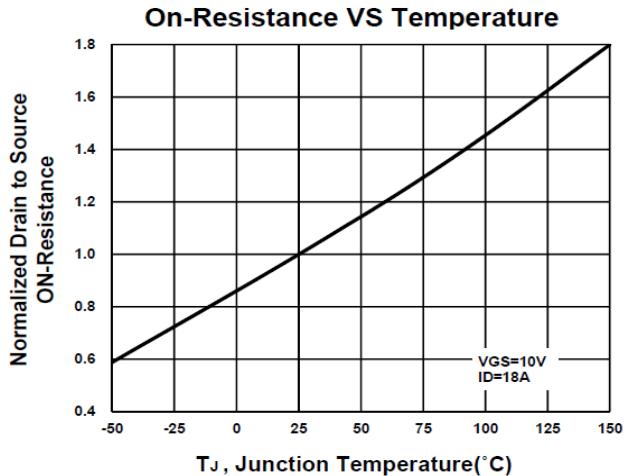
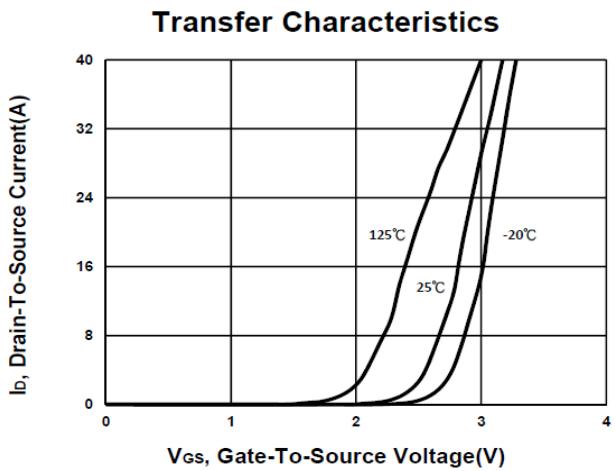
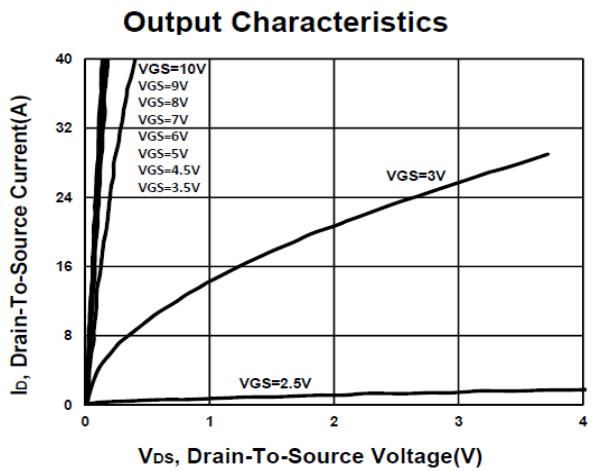
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Package limitation current is 26A.

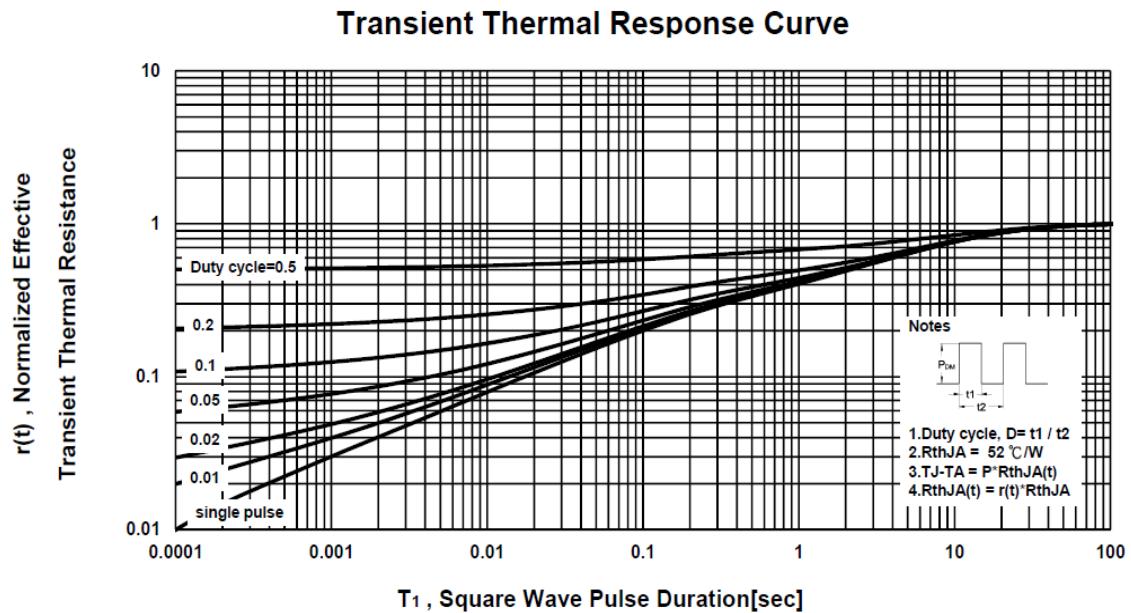
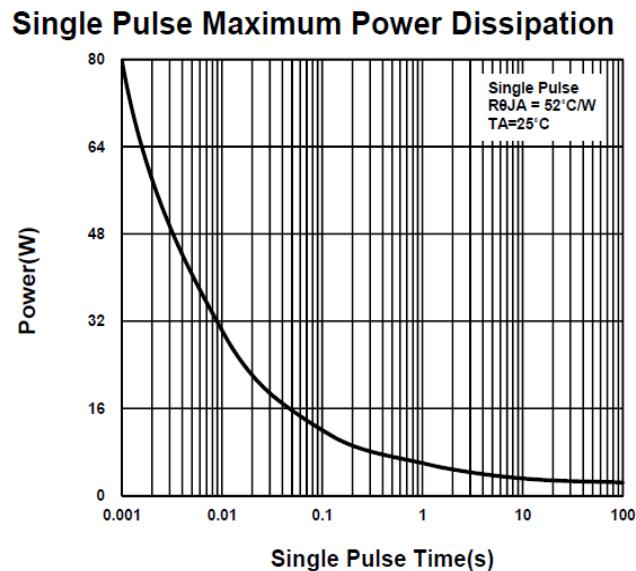
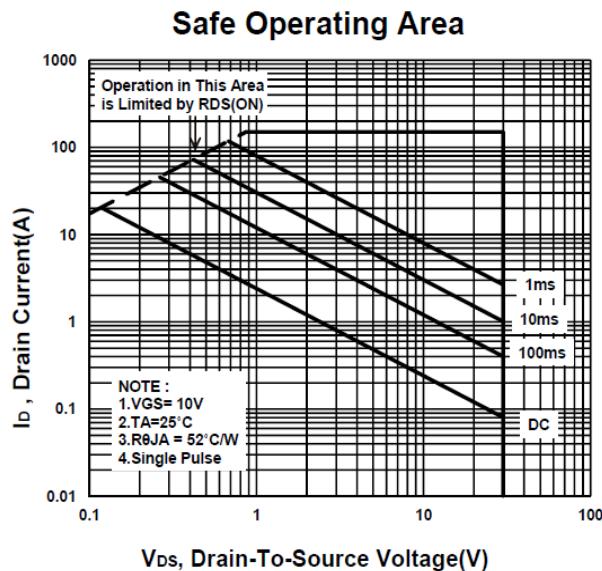
PK648BA

N-Channel Enhancement Mode MOSFET



PK648BA

N-Channel Enhancement Mode MOSFET



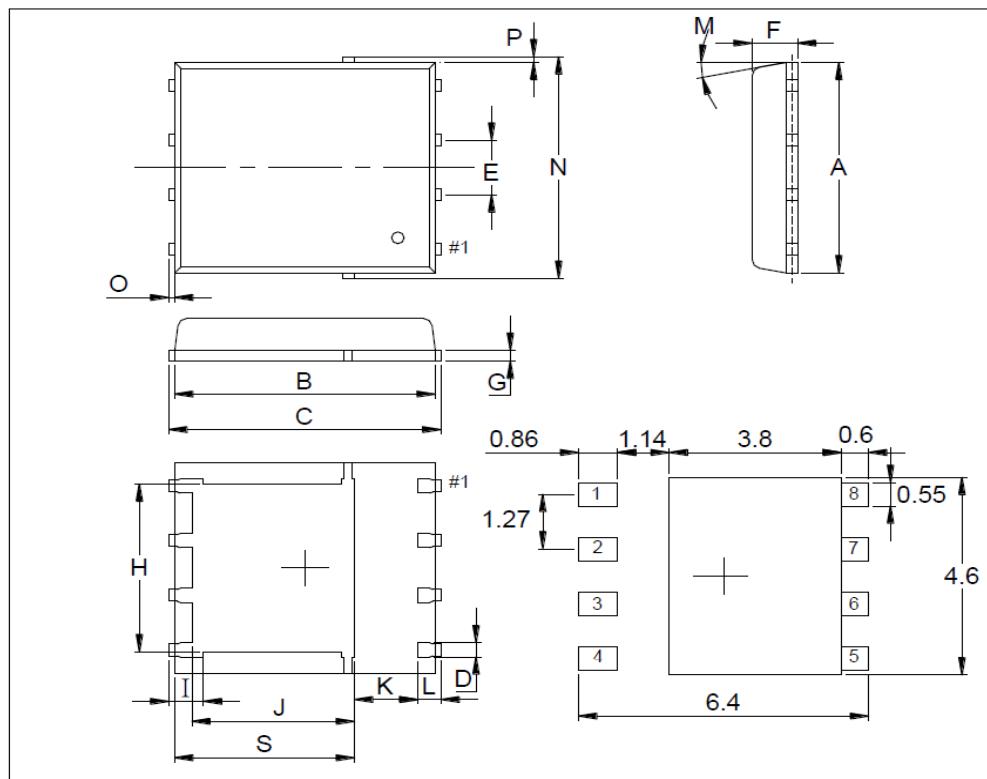
PK648BA

N-Channel Enhancement Mode MOSFET

Package Dimension

PDFN 5x6P MECHANICAL DATA

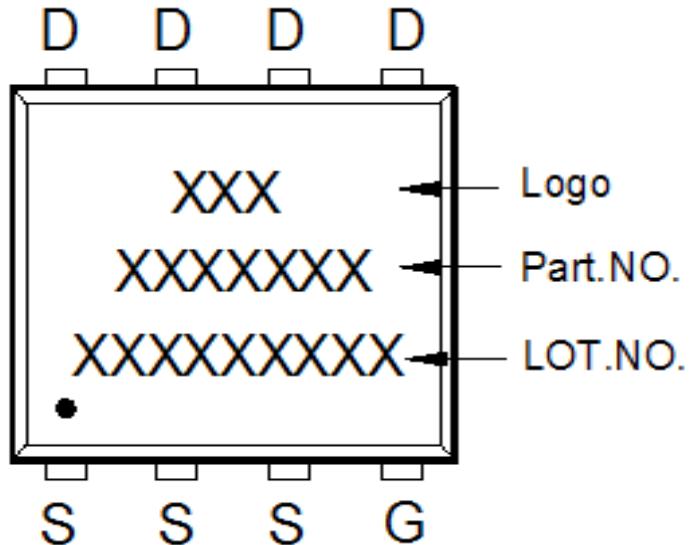
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8		5.15	J	3.34		3.9
B	5.42		5.9	K	0.9		
C	5.9		6.35	L	0.38		0.711
D	0.3		0.51	M	0°		12°
E	1.17	1.27	1.37	N	4.8		5.4
F	0.8	1	1.2	O	0.05		0.36
G	0.15		0.35	P	0.05		0.25
H	3.67		4.31	S	3.73		4.19
I	0.38		0.71				



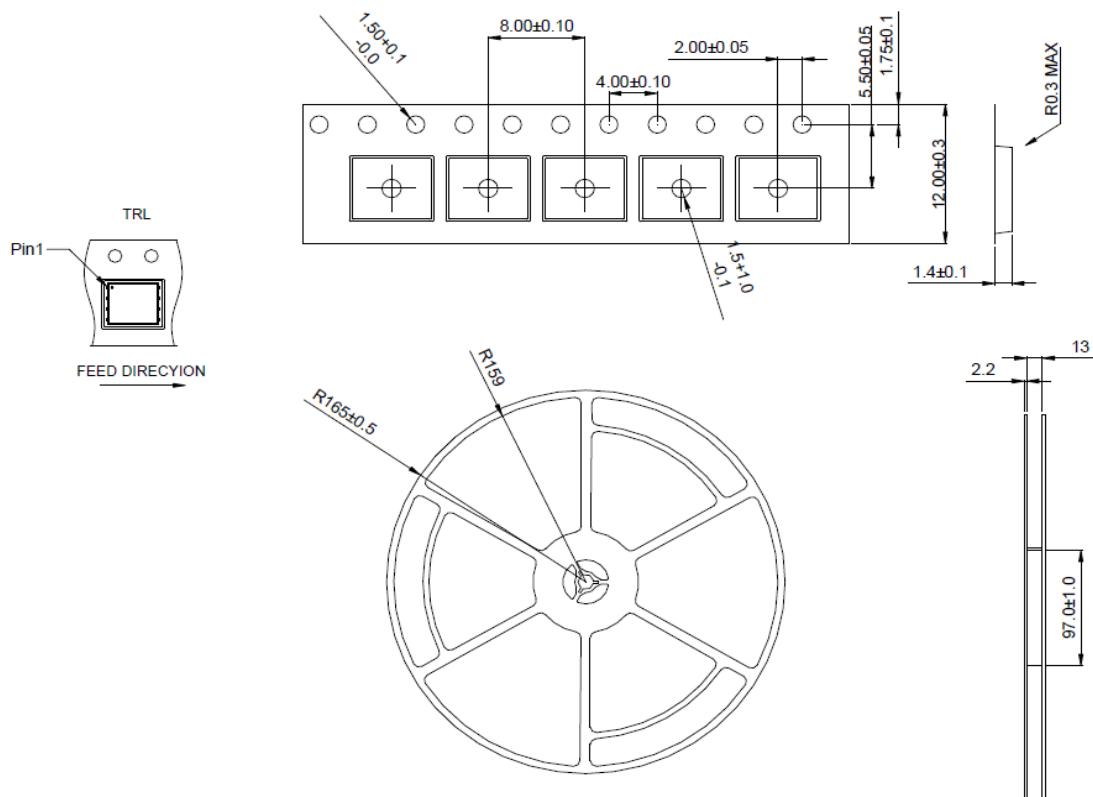
PK648BA

N-Channel Enhancement Mode MOSFET

A. Marking Information



B. Tape&Reel Information: 3000pcs/Reel

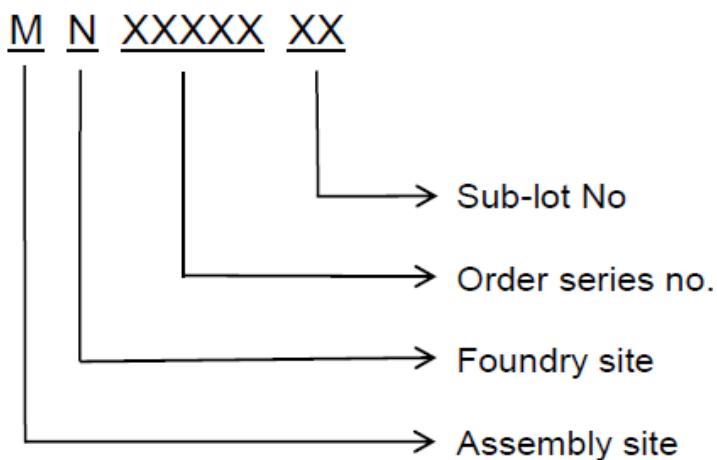


PK648BA

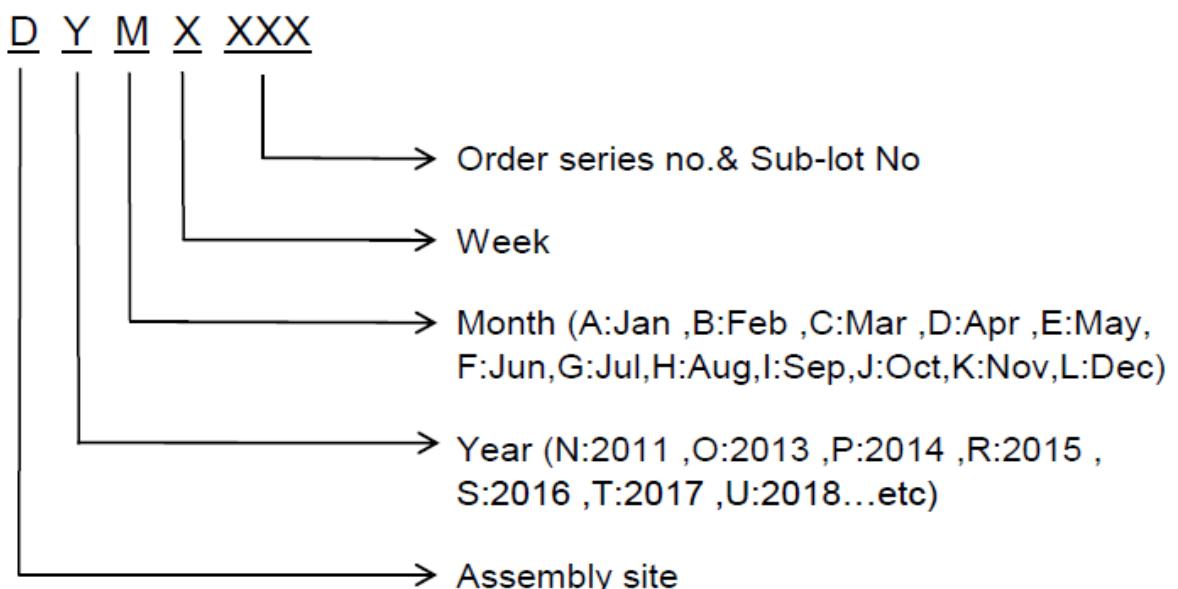
N-Channel Enhancement Mode MOSFET

C. Lot No.&Date Code rule

1.Lot No.



2.Date Code



PK648BA N-Channel Enhancement Mode MOSFET

D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm	
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)	
3	U-NIKC	Height: 4 mm	
4	Package	Height: 2 mm	
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12	
6	Device	Height: 3 mm (Max: 16 Digit)	
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot	
8	D/C	Height: 3 mm (Max: 7 Digit)	
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed	
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial	
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial	
12	Scan information	Device / Lot / D/C / QTY , Insert “ / “ between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least	